

SOT685-3

plastic, thermal enhanced very thin small outline package; no leads; 8 terminals

10 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON8; QFPAK
Package type industry code	HVSON8; QFPAK
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	MO-229
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	30-8-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	0.8	-	0.85	1	mm
e	nominal pitch	-	-	1.27	-	mm
n ₂	actual quantity of termination	-	-	8	-	

2. Package outline

Fig. 1. Package outline HVSON8; QFPAK (SOT685-3)



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3. Legal information

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